

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	73	"438"/\$.ccls. and copper with damascene and (polyarylene polysiloxane methylsilsesquioxane) and (sin sioc nitride oxide)	USPAT	OR	OFF	2005/10/21 16:05
L3	68	"438"/\$.ccls. and copper with damascene and (polyarylene polysiloxane methylsilsesquioxane) and (sin sioc nitride oxide) with layer	USPAT	OR	OFF	2005/10/21 16:05
L4	31	"438"/\$.ccls. and copper with damascene and (polyarylene polysiloxane methylsilsesquioxane) and (sin sioc nitride oxide) with layer same (cmp or polish\$)	USPAT	OR	OFF	2005/10/21 16:47
L5	1622	"438"/\$.ccls. and trench with isolation same polish\$	USPAT	OR	OFF	2005/10/21 16:49
L6	1216	"438"/\$.ccls. and trench with isolation same polish\$ same (oxide or sog or glass)	USPAT	OR	OFF	2005/10/21 17:00
L10	860	"438"/\$.ccls. and trench with isolation same polish\$ same (oxide or sog or glass) same substrate	USPAT	OR	OFF	2005/10/21 17:01
L11	649	"438"/\$.ccls. and trench with isolation same polish\$ same (oxide or sog or glass) same substrate with trench	USPAT	OR	OFF	2005/10/21 17:01
S1	6923	polish\$ with pad	USPAT	OR	OFF	2005/10/20 14:44
S2	2301	polish\$ with pad same (cell recess\$ space\$ open\$ void\$empty)	USPAT	OR	OFF	2005/10/20 14:46
S3	2315	polish\$ with pad same (cell or cellular recess\$ space\$ open\$ void\$empty)	USPAT	OR	OFF	2005/10/20 14:46
S4	2478	polish\$ with pad same (cell or cellular recess\$ space\$ open\$ void\$empty matrix)	USPAT	OR	OFF	2005/10/20 14:47
S5	2528	polish\$ with pad same (cell or cellular recess\$ space\$ open\$ void\$empty matrix)	USPAT	OR	OFF	2005/10/20 14:51
S6	1493	polish\$ with pad with (cell or cellular recess\$ space\$ open\$ void\$empty matrix)	USPAT	OR	OFF	2005/10/20 15:37
S7	94	polish\$ with pad with (cell or cellular recess\$ space\$ open\$ void\$empty matrix) and pad with (non adj abrasive or nonabrasive)	USPAT	OR	OFF	2005/10/20 15:40

S8	61	polish\$ with pad with (cell or cellular recess\$ void\$ empty matrix) and pad with (non adj abrasive or nonabrasive)	USPAT	OR	OFF	2005/10/20 15:42
S9	1	polish\$ with pad with (cell or cellular recess\$ void\$ empty matrix) same (microm meter nanometer meter centimet cm mm milimeter m) and pad with (non adj abrasive or nonabrasive)	USPAT	OR	OFF	2005/10/20 15:46
S10	1	polish\$ with pad with (cell or cellular recess\$ void\$ empty) same (matrix matric\$4) same (microm meter nanometer meter centimet cm mm milimeter m)	USPAT	OR	OFF	2005/10/20 15:47
S11	25	polish\$ with pad with (cell or cellular recess\$ void\$ empty) same (matrix matric\$4)	USPAT	OR	OFF	2005/10/20 16:18
S12	1	"2000349053" "349053"	JPO	OR	OFF	2005/10/20 15:59
S13	2	2002/0078632 "0078632"	USPAT	OR	OFF	2005/10/20 16:00
S14	2	2002/0078632 "0078632"	US-PGPUB; USPAT	OR	OFF	2005/10/20 16:01
S15	21627	hasegawa	US-PGPUB; USPAT	OR	OFF	2005/10/20 16:01
S16	1538	hasegawa and pad	US-PGPUB; USPAT	OR	OFF	2005/10/20 16:01
S17	205	hasegawa and pad same polish\$	US-PGPUB; USPAT	OR	OFF	2005/10/20 16:04
S18	40	hasegawa.inv. and pad same polish\$	US-PGPUB; USPAT	OR	OFF	2005/10/20 16:04
S19	5	("3504457"   "6354915"   "6419556"   "6517426").PN. OR ("6848974").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/20 16:49
S20	2313	(poros porous porosity) and polish\$4 with pad	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/20 16:50
S21	988	(poros porous porosity pore void cavity) same (size length volume) and polish\$4 with pad	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/20 16:51
S22	588	(poros porous porosity pore void cavity) with (size length volume) and polish\$4 with pad	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/20 16:51
S23	477	(poros porous porosity pore void cavity) with (size length volume) and polish\$4 adj pad	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/20 17:13

S24	173	(poros porous porosity pore void cavity) with (size length volume) and polish\$4 adj pad and (poros porous porosity pore void cavity) with volume and (cmp or semiconductor or cheical adj mechanical)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/21 08:01
S25	27	("6062968").URPN.	USPAT	OR	OFF	2005/10/21 08:05
S26	1	("6790883").URPN.	USPAT	OR	OFF	2005/10/21 10:27
S27	8	("20020173231"   "20030060138"   "20030129931"   "20040014413"   "20040063391"   "20040118051"   "6645264"   "6790883").PN. OR ("6903021").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/21 10:59
S28	1	("2002/0098789").URPN.	USPAT	OR	OFF	2005/10/21 13:30